## LNJ852W86RA

### Hight Bright Surface Mounting Chip LED

SV (Side View) -0.4 Type

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Power dissipation	$P_{\mathrm{D}}$	55	mW	
Forward current	$I_{\mathrm{F}}$	20	mA	
Pulse forward current *	$I_{FP}$	60	mA	
Reverse voltage	V <sub>R</sub>	4	V	
Operating ambient temperature	T <sub>opr</sub>	-30 to +85	°C	
Storage temperature	T <sub>stg</sub>	-40 to +100	°C	

Note) \*: The condition of I<sub>FP</sub> is duty 10%, Pulse width 1 msec.

#### ■ Lighting Color

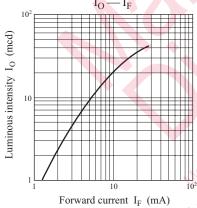
• Soft Orange

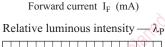
#### ■ Electro-Optical Characteristics $T_a = 25$ °C±3°C

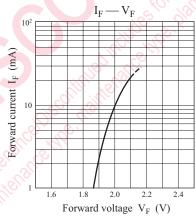
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *1	$I_{O}$	$I_F = 5 \text{ mA}$	6.0	9.0	23.0	mcd
Reverse current	$I_R$	$V_R = 4 V$			100	μΑ
Forward voltage	$V_{\rm F}$	$I_F = 5 \text{ mA}$	ili x	1.95	2.30	V
Peak emission wavelength	$\lambda_{ m P}$	$I_F = 5 \text{ mA}$	91100	610		nm
Dominant emission wavelength *2	$\lambda_{ m d}$	$I_F = 5 \text{ mA}$	597	605	610	nm
Spectral half band width	Δλ	$I_F = 5 \text{ mA}$	Jilli.	15		nm

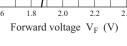
Note) \*1: Measurement tolerance: ±20%

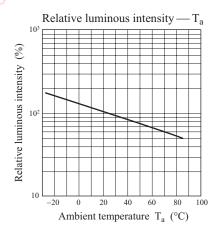
<sup>\*2:</sup> Measurement tolerance: ±3 nm

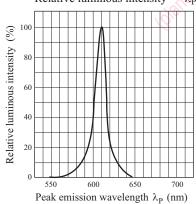


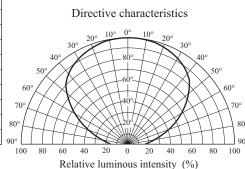


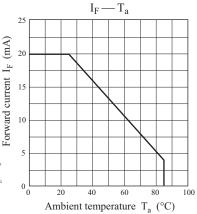






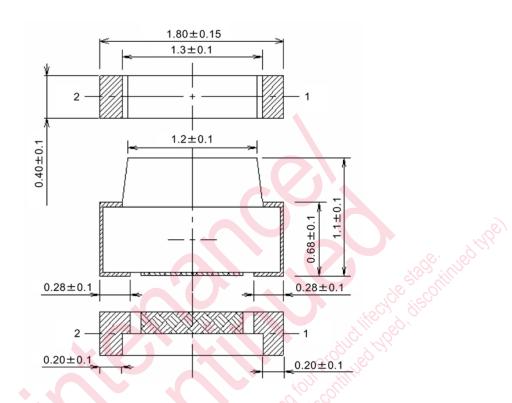






■ Package (Unit: mm)

## KLTFSN2K5200



- Pin name
  - 1: Anode
  - 2: Cathode

2 Ver. CEK

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